

# UNITED STATES PATENT AND TRADEMARK OFFICE



APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/788,503	02/21/2001	Hideki Tanaka	00N033-US	6750	
21254	7590 03/27/2003				
	& GIBB, PLLC	EXAMINER			
SUITE 200	COURTHOUSE ROAD		NGUYEN, KHIEM D		
VIENNA, V	A 22182-3817		ART UNIT	PAPER NUMBER	
			2823	$\overline{q}$	
			DATE MAILED: 03/27/2003	/	

Please find below and/or attached an Office communication concerning this application or proceeding.

			Application No.	Applicant(s)	
			09/788,503	TANAKA, HIDEKI	1
	Offic	Action Summary	Examiner	Art Unit	
			Khiem D Nguyen	2823	
Period fo		LING DATE of this communication app	ears on the cover shet w	rith the correspondence address	
THE N - Exter after - If the - If NO - Failui - Any re	MAILING E asions of time r SIX (6) MONTI period for reply period for reply re to reply withing eply received be d patent term a	O STATUTORY PERIOD FOR REPLY DATE OF THIS COMMUNICATION. may be available under the provisions of 37 CFR 1.13 HS from the mailing date of this communication. y specified above is less than thirty (30) days, a reply y is specified above, the maximum statutory period win the set or extended period for reply will, by statute, by the Office later than three months after the mailing adjustment. See 37 CFR 1.704(b).	66(a). In no event, however, may a within the statutory minimum of thi fill apply and will expire SIX (6) MO cause the application to become A date of this communication, even it	reply be timely filed  rly (30) days will be considered timely.  NTHS from the mailing date of this communicatio  BANDONED (35 U.S.C. § 133).	n.
1)🖂	Respons	ive to communication(s) filed on <u>08 J</u>	<u>anuary 2003</u> .		
2a)□	This action	on is <b>FINAL</b> . 2b)⊠ Thi	s action is non-final.		
3) 🗌 Dispositi		s application is in condition for allowal accordance with the practice under the ms			is
4)🖂	Claim(s)	<u>1-11 and 13-27</u> is/are pending in the	application.	•	
	4a) Of the	above claim(s) is/are withdraw	n from consideration.		
5)	Claim(s) _	is/are allowed.			
6)⊠	Claim(s) 1	<i>-11 and 13-27</i> is/are rejected.			
7) 🗀	Claim(s) _	is/are objected to.	•		
8) 🗌 Application		are subject to restriction and/or	election requirement.		
'' _		cation is objected to by the Examiner	•		
·	•	g(s) filed on 21 February 2001 is/are		iected to by the Examiner	
		may not request that any objection to the		•	
│ │ 11)[☐ T		sed drawing correction filed on		disapproved by the Examiner.	
'-	• •	ed, corrected drawings are required in rep		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	
12)□ T		r declaration is objected to by the Exa	-		
Priority u	nder 35 U	.S.C. §§ 119 and 120			
		dgment is made of a claim for foreign	priority under 35 U.S.C.	§ 119(a)-(d) or (f).	
1		Some * c) None of:	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	0 ( - ) ( - ) ( - )	
·		tified copies of the priority documents	have been received.		
		tified copies of the priority documents		Application No.	
	V <u>_</u>	ies of the certified copies of the prior			
		application from the International Bur ached detailed Office action for a list o	eau (PCT Rule 17.2(a)).	•	
14)∐ A	cknowledg	ment is made of a claim for domestic	priority under 35 U.S.C.	§ 119(e) (to a provisional applicati	on).
		anslation of the foreign language prov gment is made of a claim for domestic	• •		
Attachment	(s)				
2) Notice	of Draftsper	es Cited (PTO-892) son's Patent Drawing Review (PTO-948) sure Statement(s) (PTO-1449) Paper No(s) <u>5.</u>	5) Notice of	Summary (PTO-413) Paper No(s) Informal Patent Application (PTO-152)	
U.S. Patent and Tra PTO-326 (Rev		Office Act	ion Summary	Part of Paper No.	9

#### **DETAILED ACTION**

The non-final rejection as set forth in paper No. (9) is withdrawn in response to applicants' amendments.

A new rejection is made as set forth in this Office Action.

Claims (1-11 and 13-27) are pending in the application.

## Claim Rejections - 35 USC § 112

The following is a quotation of the second paragraph of 35 U.S.C. 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

Claims 6, 8, 10 and 25 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

Claims 6, 8, 10 and 25 recite the limitation "substantially perpendicular" the term "substantially" is often used in conjunction with another term to describe a particular characteristic of the claimed invention. It is a broad term. In re Nehrenberg, 280 F.2d 161, 126 USPQ 383 (CCPA 1960).

### Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1-11 and 13-27 are rejected under 35 U.S.C. 103(a) as being unpatentable over the applicant's admitted prior art (AAPA) of this application in view of

Japanese Laid Open Patent Publication (JLOPP) Hei 6-196609 and Kim et al. (U.S. Patent 6,016,176).

AAPA teaches a tape carrier type semiconductor device comprising (See Description of the Related Art on pages 1-2 of this application and FIGS. 10A-B):

a flexible substrate 62 (page 1, line 11) on whose surface wiring is formed wherein the flexible substrate comprises a resin on a first side of the flexible substrate wherein the resin including a first heat expansion coefficient and a solder resist on a second side of the flexible substrate wherein the solder resist including a second heat expansion coefficient (page 1, line 22 to page 2, line 3);

a driver circuit 63 which is mounted on the flexible substrate and drives a device connected to the flexible substrate (page 1, lines 11-12);

the flexible substrate includes a plurality of first slits 66 (page 1, line 13) such that the first slit comprises a first sub-slit and a second sub-slit (FIG. 10A-B) wherein the first slits comprises a stress-releasing slit 67 (page 1, line 13) and wherein the flexible substrate comprises a terminal area adjacent the first slits (page 1, lines 15-17) such that the first slits is situated between the driver circuit and the terminal area wherein the first slits comprises a rectangular shape with a longitudinal side parallel to the terminal area (FIGS. 10A-B); and

wherein the flexible substrate includes a second slit for folding the tape carrier type semiconductor device.

AAPA fails to explicitly disclose wherein the first slit (or plurality of first slits) having a connector (or plurality of connectors) situated intermediate thereto

for connecting both sides of the first slit to reduce warpage as recited in present claims 1, 10 and 13.

JLOPP discloses the flexible substrate includes a plurality of slits having multiple connectors situated intermediate thereto for connecting both sides of the slits to prevent warping of the substrate (Citation 2, lines 1-10). It would have been obvious to one of ordinary skill in the art at the time of the invention to combine the teaching of AAPA and JLOPP to enable the first slits of AAPA to be formed.

AAPA fails to explicitly disclose wherein the flexible substrate includes a rib formed "substantially" perpendicular to the plurality of the first slits as recited in present claims 6, 10 and 17.

Kim discloses the flexible substrate 32 includes a rib 34 formed "substantially" perpendicular to the plurality of slits 18 (col. 3, lines 16-30 and FIGS. 1-5d). It would have been obvious to one of ordinary skill in the art at the time of the invention to combine the teaching of AAPA, JLOPP and Kim to enable the rib of AAPA to be formed.

None of the references explicitly discloses the warpage percentage of the tape carrier type semiconductor device as recited in present claim 24. However, there is no evidence indicating that the warpage percentage of the tape carrier type semiconductor device is critical and it has been held that it is not inventive to discover the optimum or workable percentage of a result-effective variable within given prior art conditions by routine experimentation. See MPEP 2144.05.

#### Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Khiem D Nguyen whose telephone number is (703) 306-0210. The examiner can normally be reached on Monday-Friday (8:00 AM - 5:00 PM).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Chaudhuri Olik can be reached on (703) 306-2794. The fax phone numbers for the organization where this application or proceeding is assigned are (703) 746-9179 for regular communications and (703) 746-9179 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

K.N. March 21, 2003

George Fourson
Primary Examiner

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